

FAST CMOS 16-BIT BIDIRECTIONAL TRANSCEIVER

IDT54/74FCT162245T/AT/CT

FEATURES:

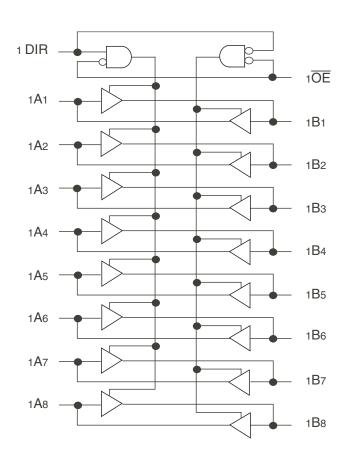
- 0.5 MICRON CMOS Technology
- · High-speed, low-power CMOS replacement for ABT functions
- Typical tsk(o) (Output Skew) < 250ps
- Low input and output leakage ≤ 1µA (max.)
- ESD > 2000V per MIL-STD-883, Method 3015; > 200V using machine model (C = 200pF, R = 0)
- · Balanced Output Drivers:
 - ±24mA (industrial)
 - ±16mA (military)
- · Reduced system switching noise
- Typical Volp (Output Ground Bounce) < 0.6V at Vcc = 5V, TA = 25°C
- Available in the following packages:
 - Industrial: SSOP, TSSOP
 - Military: CERPACK

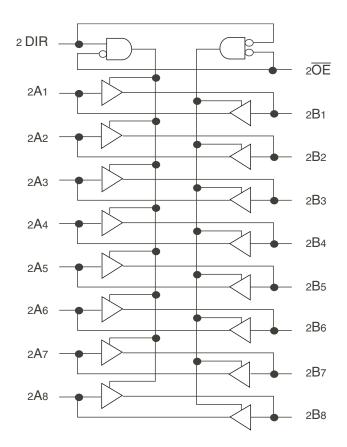
DESCRIPTION:

The FCT162245T 16-bit transceiver is built using advanced dual metal CMOS technology. These high-speed, low-power transceivers are ideal for synchronous communication between two buses (A and B). The Direction and Output Enable controls operate these devices as either two independent 8-bit transceivers or one 16-bit transceiver. The direction control pin (xDIR) controls the direction of data flow. The output enable pin (x \overline{OE}) overrides the direction control and disables both ports. All inputs are designed with hysteresis for improved noise margin.

The FCT162245T has balanced output drive with current limiting resistors. This offers low ground bounce, minimal undershoot, and controlled output fall times–reducing the need for external series terminating resistors. The FCT162245T is a plug-in replacement for the FCT16245T and ABT16245 for on-board interface applications.

FUNCTIONAL BLOCK DIAGRAM





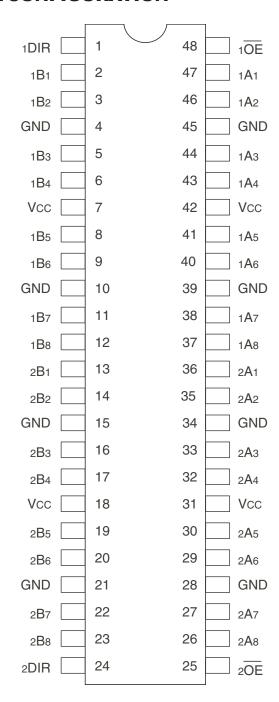
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MILITARY AND INDUSTRIAL TEMPERATURE RANGES

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PIN CONFIGURATION



SSOP/ TSSOP/ CERPACK TOP VIEW

ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Description	Max	Unit
VTERM ⁽²⁾	Terminal Voltage with Respect to GND	-0.5 to +7	V
VTERM ⁽³⁾	Terminal Voltage with Respect to GND	-0.5 to Vcc+0.5	V
Tstg	Storage Temperature	-65 to +150	°C
lout	DC Output Current	-60 to +120	mA

NOTES:

- 1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- 2. All device terminals except FCT162XXXT AND FCT166XXXT (A-Port) Output and I/O terminals.
- 3. Output and I/O terminals terminals for FCT162XXXT AND FCT166XXXT (A-Port).

CAPACITANCE (TA = +25°C, F = 1.0MHz)

Symbol	Parameter ⁽¹⁾	Conditions	Тур.	Max.	Unit
CIN	Input Capacitance	VIN = 0V	3.5	6	pF
Соит	Output Capacitance	Vout = 0V	3.5	8	pF

NOTE:

1. This parameter is measured at characterization but not tested.

PIN DESCRIPTION

Pin Names	Description			
xŌĒ	x OE Output Enable Inputs (Active LOW)			
xDIR	Direction Control Input			
x A x Side A Inputs or 3-State Outputs				
x B x Side B Inputs or 3-State Outputs				

FUNCTION TABLE(1)

Inp	uts	
х ОЕ	xDIR	Outputs
L	L	Bus B Data to Bus A
L	Н	Bus A Data to Bus B
Н	Х	High Z State

NOTE:

1. H = HIGH Voltage Level

L = LOW Voltage Level

X = Don't Care

Z = High-Impedance

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Industrial: TA = -40°C to +85°C, VCC = $5.0V \pm 10\%$; Military: TA = -55°C to +125°C, VCC = $5.0V \pm 10\%$

Symbol	Parameter	Test Condit	ions ⁽¹⁾	Min.	Typ. ⁽²⁾	Max.	Unit
VIH	Input HIGH Level	Guaranteed Logic HIGH Level		2	_	_	V
VIL	Input LOW Level	Guaranteed Logic LOW Level		_	_	0.8	V
Іін	Input HIGH Current (Input pins) ⁽⁵⁾	Vcc = Max.	VI = VCC	_	_	±1	μA
	Input HIGH Current (I/O pins) ⁽⁵⁾			_	_	±1	
lıL	Input LOW Current (Input pins) ⁽⁵⁾		VI = GND	_	_	±1	
	Input LOW Current (I/O pins) ⁽⁵⁾			_	_	±1	
Іоzн	High Impedance Output Current	Vcc = Max.	Vo = 2.7V	_	_	±1	μΑ
lozl	(3-State Output pins) ⁽⁵⁾	Vo = 0.5V		_	_	±1	
Vik	Clamp Diode Voltage	VCC = Min., IIN = -18mA			-0.7	-1.2	V
los	Short Circuit Current	Vcc = Max., Vo = GND ⁽³⁾		-80	-140	-250	mA
Vн	Input Hysteresis	_			100		mV
ICCL ICCH ICCZ	Quiescent Power Supply Current	Vcc = Max. Vin = GND or Vcc		ſ	5	500	μA

OUTPUT DRIVE CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Unit
IODL	Output LOW Current	$VCC = 5V$, $VIN = VIH or VIL$, $VO = 1.5V^{(3)}$		60	115	200	mA
lodh	Output HIGH Current	$VCC = 5V$, $VIN = VIH or VIL$, $VO = 1.5V^{(3)}$		-60	–115	-200	mA
Vон	Output HIGH Voltage	Vcc = Min	IOH = -16mA MIL	2.4	3.3	_	V
		VIN = VIH or VIL	Ioн = -24mA IND				
Vol	Output LOW Voltage	Vcc = Min	IOH = 16mA MIL	_	0.3	0.55	V
		VIN = VIH or VIL	Ioн = 24mA IND				

NOTES:

- 1. For conditions shown as Min. or Max., use appropriate value specified under Electrical Characteristics for the applicable device type.
- 2. Typical values are at Vcc = 5.0V, +25°C ambient.
- 3. Not more than one output should be tested at one time. Duration of the test should not exceed one second.
- 4. Duration of the condition can not exceed one second.
- 5. This test limit for this parameter is $\pm 5\mu A$ at $T_A = -55^{\circ}C$.

POWER SUPPLY CHARACTERISTICS

Symbol	Parameter	Test Condition	ons ⁽¹⁾	Min.	Тур.(2)	Max.	Unit
Δlcc	Quiescent Power Supply Current TTL Inputs HIGH	Vcc = Max. $Vin = 3.4V^{(3)}$		_	0.5	1.5	mA
ICCD	Dynamic Power Supply Current ⁽⁴⁾	Vcc = Max. Outputs Open xOE = xDIR = GND One Input Toggling 50% Duty Cycle	VIN = VCC VIN = GND	1	8	100	μΑ/ MHz
Ic	Total Power Supply Current ⁽⁶⁾	Vcc = Max. Outputs Open fi = 10MHz	VIN = VCC VIN = GND	_	0.6	1.5	mA
		50% Duty Cycle xOE = xDIR = GND One Bits Togging	VIN = 3.4V VIN = GND	_	0.9	2.3	
		Vcc = Max. Outputs Open fi = 2.5MHz	VIN = VCC VIN = GND	_	2.4	4.5 ⁽⁵⁾	
		50% Duty Cycle xOE = xDIR = GND Sixteen Bits Togging	VIN = 3.4V VIN = GND	_	6.4	16.5 ⁽⁵	

NOTES:

- 1. For conditions shown as Min. or Max., use appropriate value specified under Electrical Characteristics for the applicable device type.
- 2. Typical values are at Vcc = 5.0V, +25°C ambient.
- 3. Per TTL driven input (VIN = 3.4V). All other inputs at Vcc or GND.
- 4. This parameter is not directly testable, but is derived for use in Total Power Supply Calculations.
- 5. Values for these conditions are examples of the Icc formula. These limits are guaranteed but not tested.
- 6. IC = IQUIESCENT + INPUTS + IDYNAMIC
 - $IC = ICC + \Delta ICC DHNT + ICCD (fcpNcp/2 + fiNi)$
 - Icc = Quiescent Current (IccL, IccH and Iccz)
 - ΔICC = Power Supply Current for a TTL High Input (VIN = 3.4V)
 - DH = Duty Cycle for TTL Inputs High
 - NT = Number of TTL Inputs at DH
 - ICCD = Dynamic Current caused by an Input Transition Pair (HLH or LHL)
 - fcp = Clock Frequency for Register Devices (Zero for Non-Register Devices)
 - NCP = Number of Clock Inputs at fcP
 - fi = Input Frequency
 - Ni = Number of Inputs at fi

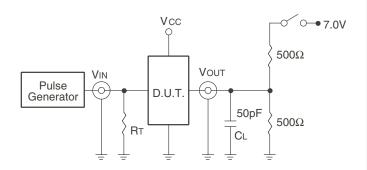
SWITCHING CHARACTERISTICS OVER OPERATING RANGE

			54FCT	162445T	54/74FCT162245AT			54/74FCT162245CT					
			М	il.	In	d.	M	il.	Ir	ıd.	M	lil.	
Symbol	Parameter	Condition ⁽¹⁾	Min.(2)	Max.	Min.(2)	Max.	Min.(2)	Max.	Min.(2)	Max.	Min.(2)	Max.	Unit
t PLH	Propagation Delay	CL = 50pF	1.5	7.5	1.5	4.6	1.5	4.9	1.5	3.5	1.5	4.5	ns
tphL	A to B, B to A	$RL = 500\Omega$											
tpzh	Output Enable Time		1.5	10	1.5	6.2	1.5	6.5	1.5	4.4	1.5	6.2	ns
tPZL	xOE to A or B												
tphz	Output Disable Time		1.5	10	1.5	5	1.5	6	1.5	4	1.5	5.2	ns
tPLZ	xOE to A or B												
tpzh	Output Enable Time		1.5	10	1.5	6.2	1.5	6.5	1.5	4.8	1.5	6.2	ns
tpzl	xDIR to A or B(4)												
tphz	Output Disable Time		1.5	10	1.5	5	1.5	6	1.5	4	1.5	5.2	ns
tplz	xDIR to A or B(4)												
tsk(o)	Output Skew ⁽³⁾		_	0.5	_	0.5	_	0.5	_	0.5	_	0.5	ns

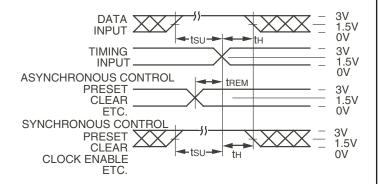
NOTES

- 1. See test circuit and waveforms.
- 2. Minimum limits are guaranteed but not tested on Propagation Delays.
- 3. Skew between any two outputs of the same package switching in the same direction. This parameter is guaranteed by design.
- 4. This parameter is guaranteed but not tested.

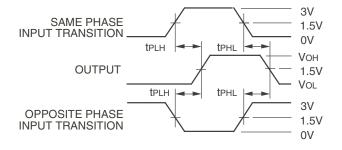
TEST CIRCUITS AND WAVEFORMS



Test Circuits for All Waveforms



Set-up, Hold, and Release Times



Propagation Delay

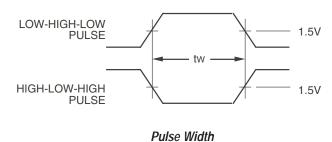
SWITCH POSITION

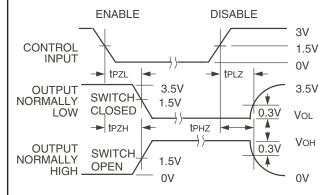
Test	Switch
Open Drain Disable Low Enable Low	Closed
All Other Tests	Open

DEFINITIONS:

CL = Load capacitance: includes jig and probe capacitance.

RT = Termination resistance: should be equal to Zout of the Pulse Generator.



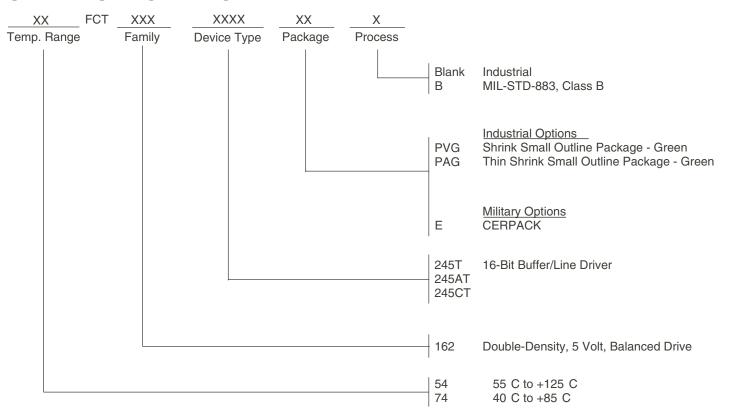


Enable and Disable Times

NOTES:

- 1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.
- 2. Pulse Generator for All Pulses: Rate \leq 1.0MHz; tr \leq 2.5ns; tr \leq 2.5ns.

ORDERING INFORMATION



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TOYOSU FORESIA, 3-2-24 Toyosu, Koto-ku, Tokyo 135-0061, Japan www.renesas.com

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